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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Eng-Chew Cheah
of:

Application No.: 09/863,652

Group Art Unit: 2814

Filed: May 22, 2001

Examiner: To be assigned

For: Multi-Tiered Lead Package For Attorney Docket No.: 9818-0050-999
An Integrated Circuit

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above identified application as follows:

IN THE SPECIFICATION:

A marked up version of the revised paragraph, showing additions are included in the Appendix.

Page 1, first paragraph should read as follow:

AI --This application claims priority to the provisional patent application entitled,
"Multi-tiered Lead Package for an Integrated Circuit," serial number 60/236,495, filed
September 29, 2000.--



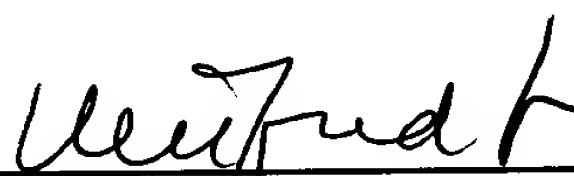
REMARKS

The Applicant submits herewith a Preliminary Amendment and a Supplemental Declaration to correct a typographical error in the specification and in the originally submitted Declaration.

No fee is believed due for filing this preliminary amendment. However, if a fee is due, please charge such fee to Pennie & Edmonds LLP's Deposit Account No. 16-1150.

Respectfully submitted,

Date November 7, 2001



Wilfred H. Lam 41,923
(Reg. No.)
For Francis E. Morris Reg. No. 24,615
PENNIE & EDMONDS LLP
3300 Hillview Avenue
Palo Alto, CA 94304
(650) 493-4935

Enclosure